DEVCOM ARMAMENTS CENTER

POTTING & ENCAPSULATION FACILITY

LABORATORY INFORMATION FACT SHEET

The Potting & Encapsulation Facility is a Precision Munitions and Instrumentations Division laboratory that utilizes potting compounds and encapsulation materials.

TECHNOLOGY/FACILITY DESCRIPTION:

The Combat Capabilities Development Command Armaments Center (DEVCOM AC) Precision Munitions and Instrumentation Division has been in the prototype development arena since the team's inception in the early 1950's. Since then, the concept of "prototype development" has been taken to new levels. Capabilities include surface mount, through-hole technologies and hand finished work. Electro-mechanical, cable and harness assembly are additional services that we provide. Complete electrical test and evaluation are available. The team has expertise in packaging, from commercial to military high G applications, packaging multiple, complex components into a single package effectively and efficiently. Experience also includes packaging other pre-engineered systems.

EQUIPMENT AND EXPERTISE AVAILABLE:

- State of the art temperature and humidity controlled encapsulation laboratory with fume hoods, slot exhauster and process equipment
- Engineers and technicians utilize specialized epoxy potting compounds, encapsulation materials and conformal coatings
- Technicians are experienced in assembling, coating and potting complex molds and various enclosures

- Engineering ~~team proficient~~ in the design and qualification of devices and assemblies for vehicle systems, weapons systems and high-G survivability and operation
- "Hands-on" design and fabrication experience
- Printed circuit board design, layout, fabrication and rework capability
- Electronics circuit troubleshooting and repair

- Electronics and electro-mechanical systems integration
- High voltage power and control systems design and testing
- Encapsulation of electronics components and systems
- Quality assurance inspections